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To the Honorable Commissioner of Patents and

ed original documents or copy thereof.

1. Name of conveying party(ies)

Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang,
Randy Hsiao-Yu and Chiang-Han DayAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: November 9, 1998

2. Name and address of receiving party(ies)

Name: Industrial Technology Research Institute

Internal Address: _____

Street Address: 195, Sec. 4, Chung Hsing RdChutung, HsinchuTaiwan, R.O.C.

City: _____ State: _____ ZIP: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: November 9, 1998

A. Patent Application No.(s)

for "Flip-Chip Ball Grid Array Package With A Heat"

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Jason Z. Lin

Internal Address: _____

Street Address: 19597 Via Monte DriveCity: Saratoga State: CA ZIP: 95070

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41) \$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jason Z. Lin

Name of Person Signing

Signature

Dec. 10, 1998
Date

Total number of pages including cover sheet, attachments, and document:

3

Mail documents to be recorded with required cover sheet information to:
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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date shown below.

Date:

Dec. 10, 1998

By:

Jason Z. Lin

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ASSIGNMENT

WHEREAS, I/we, **Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang, Randy Hsiao-Yu Lo & Chiang-Han Day** whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful improvements in **FLIP-CHIP BALL GRID ARRAY PACKAGE WITH A HEAT SLUG** (hereinafter referred to as "The Invention") for which an application for United States Letters Patent was

- ☒ executed on even date herewith;
☐ executed on _____;
☐ filed on _____, Serial No. _____;
☐ filed as PCT International Application No. _____ on _____, designating The United States of America;
☐ Patent number _____, issue on _____.

WHEREAS, **INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE** whose post office address is **No. 195, Sec. 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan, R.O.C.** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the invention that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Assignor: **Fang-Jun Leu**
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Dated this 4 day of Nov., 1998 at **Hsinchu, Taiwan**

Fang-Jun Leu
Signature

Assignor: **Rong-Shen Lee**
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Dated this 9 day of Nov. at 1998

Rong-Shen Lee
Signature

Assignor: **Hsin-Chien Huang**
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Dated this 9 day of Nov. 1998 at

H.C. Huang
Signature

ASSIGNMENT
(SUPPLEMENTAL SHEET)
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Title: FLIP-CHIP BALL GRID ARRAY PACKAGE WITH A HEAT SLUG

Inventors: Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang, Randy Hsiao-Yu Lo & Chiang-Han Day

Assignor: **Randy Hsiao-Yu Lo**

No. 2, Alley 5, Lane 289,

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Dated this 16th day of Nov. at


Signature

Assignor: **Chiang-Han Day**

3F-3, No. 18, Alley 51, Lane 400,

Ming Hu Rd., Hsinchu,

Taiwan, R.O.C.

Dated this 9 day of Nov., 1998 at


Signature

Assignor:

Dated this day of at

Signature